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ATTORNEY DOCKET NO. CONFIRMATION NO. APPLICATION NO. FILING DATE FIRST NAMED INVENTOR Michael W. Morrison 4195 03/10/2004 2269-6103US 10/797,647 (03-0954.00/U **EXAMINER** 24247 09/29/2005 TRASK BRITT LEWIS, MONICA P.O. BOX 2550 ART UNIT PAPER NUMBER SALT LAKE CITY, UT 84110 2822

DATE MAILED: 09/29/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

			AIC
	Application No.	Applicant(s)	
Office Action Summary	10/797,647	MORRISON ET AL.	
	Examiner	Art Unit	
	Monica Lewis	2822	
The MAILING DATE of this communication Period for Reply	n appears on the cover sheet with	the correspondence addre	ss
A SHORTENED STATUTORY PERIOD FOR R THE MAILING DATE OF THIS COMMUNICATI - Extensions of time may be available under the provisions of 37 C after SIX (6) MONTHS from the mailing date of this communicatio - If the period for reply specified above, the maximum statutory or Failure to reply within the set or extended period for reply will, by Any reply received by the Office later than three months after the earned patent term adjustment. See 37 CFR 1.704(b).	ON. FR 1.136(a). In no event, however, may a replon. , a reply within the statutory minimum of thirty (period will apply and will expire SIX (6) MONTH statute, cause the application to become ABAN	ly be timely filed 30) days will be considered timely. IS from the mailing date of this comminion (35 U.S.C. § 133).	unication.
Status .			
1) Responsive to communication(s) filed on	10 March 2004.		
, <u> </u>	This action is non-final.		
3) Since this application is in condition for al closed in accordance with the practice un	lowance except for formal matter	• •	erits is
Disposition of Claims			
4) ☐ Claim(s) 1-36 is/are pending in the application 4a) Of the above claim(s) is/are with 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) 1-36 are subject to restriction and subjec	hdrawn from consideration.		
Application Papers			
9)☐ The specification is objected to by the Exa			
10)☐ The drawing(s) filed on is/are: a)☐			
Applicant may not request that any objection t			
Replacement drawing sheet(s) including the c			
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for fo a) All b) Some * c) None of: 1. Certified copies of the priority docu 2. Certified copies of the priority docu 3. Copies of the certified copies of the application from the International B * See the attached detailed Office action for	ments have been received. ments have been received in App priority documents have been re ureau (PCT Rule 17.2(a)).	olication No eceived in this National Sta	nge
Attachment(s)			
1) Notice of References Cited (PTO-892)	4) Interview Sur		
 Notice of Draftsperson's Patent Drawing Review (PTO-943) Information Disclosure Statement(s) (PTO-1449 or PTO/S Paper No(s)/Mail Date 	· · · · · · · · · · · · · · · · · · ·	Mail Date ormal Patent Application (PTO-15	2)

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DETAILED ACTION

1. This action is in response to the application filed March 10, 2004.

Election/Restrictions

2. Restriction to one of the following inventions is required under 35 U.S.C. 121:

- I. Claims 1-27, drawn to a semiconductor device comprising a BGA package for a segmented voltage plane, classified in class 257, subclass 676.
- II. Claims 28-36, drawn to a process for fabricating a BGA package for a segmented voltage plane, classified in class 438, subclass 106.

Inventions II and I are related as process of making and product made. The inventions are distinct if either or both of the following can be shown: (1) that the process as claimed can be used to make other and materially different product or (2) that the product as claimed can be made by another and materially different process (MPEP § 806.05(f)). The product can be made by the following methods: a) selective deposition could be utilized instead of etching.

Because these inventions are distinct for the reasons given above and have acquired a separate status in the art as shown by their different classification, restriction for examination purposes as indicated is proper.

Applicant is reminded that upon the cancellation of claims to a non-elected invention, the inventorship must be amended in compliance with 37 CFR 1.48(b) if one or more of the currently named inventors is no longer an inventor of at least one claim remaining in the application. Any amendment of inventorship must be accompanied by a request under 37 CFR 1.48(b) and by the fee required under 37 CFR 1.17(i).

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Applicant is advised that the reply to this requirement to be complete must include an election of the invention to be examined even though the requirement be traversed (37 CFR 1.143).

3. If the Applicant selects Invention I disclosed then application contains claims directed to the following patentably distinct species of the claimed invention:

Embodiment I (Claims 1 and 2), directed to a semiconductor device comprising a die, bond pads, a dielectric film having at least one conductive trace disposed upon a surface, a via, a conductive layer disposed between the active surface of the die and the dielectric film, isolation slot, a plurality of electrical conductors and a plurality of discrete conductive elements disposed upon the surface of the dielectric film;

Embodiment II (Claims 1, 3-6 and 13-15), directed to a semiconductor device comprising a die, bond pads, a dielectric film having at least one conductive trace disposed upon a surface, a via, a conductive layer disposed between the active surface of the die and the dielectric film wherein the conductive layer is configured to operably coupled to a voltage source;

Embodiment III (Claims 1 and 7), directed to a semiconductor device comprising a die, bond pads, a dielectric film having at least one conductive trace disposed upon a surface, a via, a conductive layer disposed between the active surface of the die and the dielectric film, isolation slot that substantially segments the electrically conductive layer;

Embodiment IV (Claims 1 and 8-11), directed to a semiconductor device comprising a die, bond pads, a dielectric film having at least one conductive trace disposed upon a surface, a via, a conductive layer disposed between the active surface of the die and the dielectric film, isolation slot and longitudinal slots formed through the conductive layer and the dielectric film; Embodiment V (Claims 1 and 8-11), directed to a semiconductor device comprising a die, bond pads, a dielectric film having at least one conductive trace disposed upon a surface, a via, a conductive layer disposed between the active surface of the die and the dielectric film, isolation slot and longitudinal slots formed through the conductive layer and the dielectric film; Embodiment VI (Claims 1 and 12), directed to a semiconductor device comprising a die, bond pads, a dielectric film having at least one conductive trace disposed upon a surface, a via, a conductive layer disposed between the active surface of the die and the dielectric film wherein the dielectric film comprises a multilayer film having at least one additional layer of conductive traces, at least one additional layer dielectric layer and at least one interlayer conductive via effecting connection between the at least one conductive trace and a conductive trace of the at least one additional layer of conductive traces; Embodiment VII (Claims 16 and 17), directed to a semiconductor device comprising a die, bond pads, a dielectric film having at least one conductive trace disposed upon a top surface, a via, a conductive layer adhered to the dielectric

film, isolation slot, a plurality of electrical conductors and a plurality of discrete conductive elements disposed upon the surface of the dielectric film; Embodiment VIII (Claims 16 and 18-21), directed to a semiconductor device comprising a die, bond pads, a dielectric film having at least one conductive trace disposed upon a top surface, a via, a conductive layer adhered to the dielectric film wherein the conductive layer is configured to operably coupled to a voltage source:

Embodiment IX (Claims 16 and 22), directed to a semiconductor device comprising a die, bond pads, a dielectric film having at least one conductive trace disposed upon a surface, a via, a conductive layer disposed between the active surface of the die and the dielectric film, isolation slot that substantially segments the electrically conductive layer; and

Embodiment X (Claims 16 and 23-26), directed to a semiconductor device comprising a die, bond pads, a dielectric film having at least one conductive trace disposed upon a surface, a via, a conductive layer disposed between the active surface of the die and the dielectric film, isolation slot and longitudinal slots formed through the conductive layer and the dielectric film.

Applicant is required under 35 U.S.C. 121 to elect a single disclosed species for prosecution on the merits to which the claims shall be restricted if no generic claim is finally held to be allowable. Currently, none are generic.

Applicant is advised that a reply to this requirement must include an identification of the species that is elected consonant with this requirement, and a listing of all claims readable

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thereon, including any claims subsequently added. An argument that a claim is allowable or that all claims are generic is considered nonresponsive unless accompanied by an election.

Upon the allowance of a generic claim, applicant will be entitled to consideration of claims to additional species which are written in dependent form or otherwise include all the limitations of an allowed generic claim as provided by 37 CFR 1.141. If claims are added after the election, applicant must indicate which are readable upon the elected species. MPEP § 809.02(a).

Conclusion

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Monica Lewis whose telephone number is 571-272-1838.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on 571-272-1852. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300 for regular and after final communications. Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

ML

September 27, 2005

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